Chromium–Niobium Co-Doped Vanadium Dioxide Films: Large Temperature Coefficient of Resistance and Practically No Thermal Hysteresis of the Metal–Insulator Transition^{*}

Kenichi MIYAZAKI

Kenichi SAKAI

Keisuke SHIBUYA Megumi SUZUKI Jun-ichi FUJITA, and Akihito SAWA

We investigated the effects of chromium (Cr) and niobium (Nb) co-doping on the temperature coefficient of resistance (TCR) and the thermal hysteresis of the metal–insulator transition of vanadium dioxide (VO₂) films. We determined the TCR and thermal-hysteresis-width diagram of the $V_{1-x-y}Cr_xNb_yO_2$ films by electrical-transport measurements and we found that the doping conditions $x \ge y$ and $x + y \ge 0.1$ are appropriate for simultaneously realizing a large TCR value and an absence of thermal hysteresis in the films. By using these findings, we developed a $V_{0.90}Cr_{0.06}Nb_{0.04}O_2$ film grown on a TiO₂-buffered SiO₂/Si substrate that showed practically no thermal hysteresis while retaining a large TCR of 11.9%/K. This study has potential applications in the development of VO₂-based uncooled bolometers.

Key words :

bolometer, VO₂, metal-insulator transition, co-doping, TCR.

1. INTRODUCTION

Vanadium oxides exhibit a temperature-induced metal-insulator transition (MIT) with a discontinuous change in electrical conductivity of several orders of magnitude¹⁾. The MIT is the first-order structural transition and is also accompanied by a marked change in the optical transmittance in the infrared (IR) region. Among the various oxides of vanadium, vanadium dioxide (VO₂) is the most interesting from

an application perspective because its MIT occurs at around 340 K, which is above room temperature²⁾. An MIT above room temperature is useful in a variety of functional devices, such as electrical switches, gas sensors, smart windows, uncooled bolometers, or thermal memories³⁾. Among these devices, VO_2 -based uncooled bolometers that detect far-IR radiation have been actively studied and developed for several decades^{4–8)}.

One measure of the suitability of a material for use in

a bolometer is its temperature coefficient of resistance (TCR), which is defined as $|(1/\rho)(d\rho/dT)|$, where ρ is the resistivity or resistance and T is the temperature of the material. The TCR value of VO₂ reaches more than 70%/K near the MIT temperature $(T_{\rm MI})^{9}$, which is more than ten times that of conventional uncooled bolometer materials such as Si or Ge.¹⁰⁻¹²⁾ However, VO₂ shows a large thermal hysteresis in the ρ -T curve across the MIT. The hysteretic behavior indicates the coexistence of two phases over a finite temperature range due to superheating and supercooling effects, which is a characteristic of the first-order transition. The thermal hysteresis in the ρ -T curve results in poor measurement reproducibility in IR sensing. Consequently, thermal hysteresis has to be minimized to realize high-sensitivity uncooled bolometers based on VO₂.

Doping of VO₂ with metal ions has been employed as a means of suppressing its thermal hysteresis;^{13,14)} however, doping with metal ions also gives rise to a reduction in the TCR of VO₂. We previously conducted a systematic study of the TCR and thermal hysteresis in VO₂ doped with Cr or with Nb, and we found that there is a correlation between the TCR and thermal hysteresis, which is independent of the doping element¹⁵⁾. Our findings implied that a high TCR and the absence of thermal hysteresis were difficult to achieve simultaneously in single-element doped VO₂. However, Soltani et al. reported that co-doping of VO₂ with Ti and W suppresses thermal hysteresis more effectively than does doping with W alone¹⁶⁾. In their study, they simultaneously achieved a practical absence of thermal hysteresis and a TCR of 5.12%/K at room temperature in $V_{0.866}W_{0.014}Ti_{0.12}O_2$ films. This TCR is larger than that of conventional uncooled bolometer materials. However, it is still challenging to achieve the high TCR values in excess of 10%/K that are required for high-sensitivity uncooled bolometers.

In this study, we explored the possibility of obtaining

high TCR values with no thermal hysteresis by codoping VO₂ films with Cr and Nb. Note that V, Cr, and Nb ions are tetravalent (4+), trivalent (3+), and pentavalent (5+), respectively, and that their effective radii are 0.058, 0.062, and 0.064 nm, respectively. We previously reported that Nb doping is effective in reducing the thermal hysteresis of VO2;¹⁵⁾ however, it also causes a rapid decrease in its TCR. In contrast, the decrease in the TCR of VO₂ on doping with Cr is moderate, but Cr doping is less effective than Nb doping in reducing the thermal hysteresis. These differing effects on the TCR and thermal hysteresis might be due to the differences in the valence states and/or ionic radii of the Cr and Nb ions¹⁵⁾. Because Cr and Nb dopants are effective in maintaining large TCR values and in reducing the thermal hysteresis, respectively, co-doping with Cr and Nb might give rise to a combination of the desirable effects of the two individual ions.

From $\rho-T$ measurements on the V_{1-x-y}Cr_xNb_yO₂ films, we derived a TCR and thermal-hysteresis-width ($\Delta T_{\rm MI}$) diagram for the films. This diagram revealed that doping conditions of $x \gtrsim y$ and $x + y \ge 0.1$ are suitable for producing films that show no thermal hysteresis while retaining a large TCR. We also succeeded in producing a large TCR of 11.9%/K and practically no thermal hysteresis in V_{0.90}Cr_{0.06}Nb_{0.04}O₂ films fabricated on TiO₂-buffered SiO₂/Si substrates at process temperatures below 670 K.

2. EXPERIMENTAL

 $V_{1-x-y}Cr_xNb_yO_2$ films were grown on α -Al₂O₃ (0001) single-crystal substrates and TiO₂/SiO₂/Si (100) substrates by pulsed-laser deposition with a KrF excimer laser ($\lambda = 248$ nm). Mixed ceramic pellets consisting of V₂O₅, Cr₂O₃, and Nb₂O₅ were used as targets. The doping range for Cr was x = 0-0.12and that of Nb was y = 0-0.09. We have previously described the detailed conditions for growth of such films on $Al_2O_3^{15)}$ or $TiO_2/SiO_2/Si$ substrates¹⁷⁾. The film thickness was set at 70–110 nm, as confirmed by using a surface profiler. Note that there were no significant differences in the structural or electronic properties of the films within this thickness range. The resistivity of the films was measured by conventional four-probe methods using Ti/Au electrodes. Transport properties were examined by using a physical property measurement system (PPMS; Quantum Design), and the temperature sweep rate was set to 0.3 K/min.

3. RESULTS AND DISCUSSIONS

Fig. 1(a) and Fig. 1(b) show the ρ -T curves for the $V_{0.95-x}Cr_xNb_{0.05}O_2$ and $V_{0.95-y}Cr_{0.05}Nb_yO_2$ films on Al₂O₃ substrates with $0 \le x \le 0.12$ and $0 \le y \le$ 0.08, respectively. As a reference, the ρ -T curve for a nondoped VO_2 film is also shown in Fig. 1(b). A systematic change in $T_{\rm MI}$ with doping was observed. Here, $T_{\rm MI}$ is defined as the halfway point between the temperatures of the two peaks in the TCR for the heating and cooling processes, respectively. In addition to the change in $T_{\rm MI}{}$, the doping affected the values of the TCR and $\Delta T_{\rm MI}.$ The co-doped films showed a broadening of the MIT, and the change in ρ across the MIT for the co-doped films was smaller than that for the nondoped film. These behaviors caused a decrease in the TCR of the co-doped films. Moreover, the codoped films had a smaller $\Delta T_{\rm MI}$ compared with the nondoped film.

Fig. 2(a) and Fig. 2(b) show the dependence of $T_{\rm MI}$, the maximum TCR, and $\Delta T_{\rm MI}$ on the total dopant content x + y for the V_{0.95-x}Cr_xNb_{0.05}O₂ and V_{0.95-} _yCr_{0.05}Nb_yO₂ films on Al₂O₃ substrates, respectively. The results of single-element doping¹⁶ are also plotted for comparison. It is well known that hole doping by lower-valence elements such as Cr³⁺ or Al³⁺ raises the $T_{\rm MI}$, whereas electron doping with higher-valence

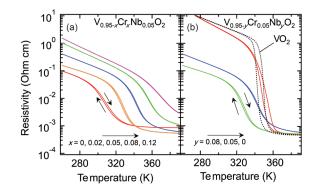


Fig. 1 Temperature dependence of the resistivity of (a) $V_{0.95-x}Cr_xNb_{0.05}O_2$ and (b) $V_{0.95-y}Cr_{0.05}Nb_yO_2$ films. As a reference, the $\rho-T$ curve for the nondoped VO₂ film (dashed line) is plotted in (b).

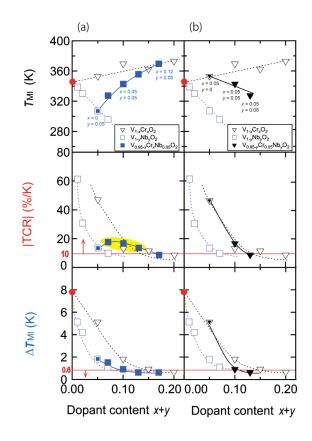


Fig. 2 Cr content (x) and Nb content (y) dependence of T_{MI} , TCR, and ΔT_{MI} for (a) $V_{0.95-x}Cr_xNb_{0.05}O_2$ and (b) $V_{0.95-y}Cr_{0.05}Nb_yO_2$ films. An increase in the TCR in the $V_{0.95-x}Cr_xNb_{0.05}O_2$ (x = 0.02, 0.05, and 0.08) films with respect to that of the $V_{0.95}Nb_{0.05}O_2$ (x = 0) film is highlighted.

elements such as Nb⁵⁺ or W⁶⁺ lowers the $T_{MI}^{15,18-20)}$. These tendencies are maintained in co-doped VO₂. As seen in the top panels in **Fig. 2**, an increase in the Cr content raised the T_{MI} of the V_{0.95-x}Cr_xNb_{0.05}O₂ films, whereas an increase in the Nb content reduced the $T_{\rm MI}$ of the V_{0.95-y}Cr_{0.05}Nb_yO₂ films. The $T_{\rm MI}$ of the V_{0.90}Cr_{0.05}Nb_{0.05}O₂ (x = y = 0.05) film was almost identical to that of the nondoped VO₂ film. These results can be explained in terms of the valence state A+ of the V ions, which can be defined as A = 4 + x - y. The $T_{\rm MI}$ of the co-doped films is dominated by the valence state of the V ions.

Doping of VO₂ with metal ions generally induces a broadening of the MIT, resulting in a decrease in the TCR. This behavior can be understood in terms of a spatial variation in the $T_{\rm MI}$, attributable to an inhomogeneity of the carrier concentration and to lattice deformation and/or defects^{21,22)}. As shown in the middle panels in Fig. 2, for singleelement doping with Cr or Nb, the maximum TCR decreased monotonically with increasing dopant content, with Nb doping having the greater effect. In contrast to single-element doping, co-doped V_{0.95-} _xCr_xNb_{0.05}O₂ films showed a nonmonotonic decrease with increasing x. The $V_{0.95-x}Cr_xNb_{0.05}O_2$ films with x = 0.02, 0.05, and 0.08 had larger TCR values than that of the $V_{0.95}Nb_{0.05}O_2$ film (x = 0), as highlighted in the middle panel in **Fig. 2(a)**. For $x \ge 0.05$ (= y), the *x* + *y* dependence of the TCR values for the $V_{0.95-}$ "Cr"Nb_{0.05}O₂ films is almost coincident with that for the $V_{1-x}Cr_xO_2$ films. This behavior can be also seen in the V_{0.95-v}Cr_{0.05}Nb_vO₂ films [the middle panel of Fig. 2(b)]. These results suggest that the presence of Cr dopant with the condition $x \gtrsim y$ is essential for obtaining large TCR values in $V_{1-x-y}Cr_xNb_yO_2$ films.

The bottom panels in **Fig. 2** show that for singleelement doping, $\Delta T_{\rm MI}$ also decreases monotonically with increasing dopant content and that it is reduced more efficiently by doping with Nb than with Cr. Note that the $\Delta T_{\rm MI}$ is defined as the difference in the temperatures at which a film has a given resistivity ($\rho_{\rm MI}$) during the heating and cooling phases. For this study, we choose $\rho_{\rm MI}$ as the value of ρ at the temperature of the TCR peak in the heating process¹⁵⁾. In contrast to the TCR value, the x + y dependence of ΔT_{MI} for both $V_{0.95}$ - $_x$ Cr $_x$ Nb $_{0.05}$ O $_2$ and $V_{0.95}$ - $_y$ Cr $_{0.05}$ Nb $_y$ O $_2$ films approached that of V_{1-y} Nb $_y$ O $_2$ films. This result suggests that the presence of Nb dopant is essential for effectively reducing the ΔT_{MI} with the minimum possible dopant content. Moreover, to realize a near absence of thermal hysteresis (defined as $\Delta T_{\text{MI}} \le 0.6$ K), a dopant content of $x + y \ge 0.1$ is required.

We therefore found that co-doping of VO₂ with Cr and Nb is an effective means of suppressing thermal hysteresis (i.e., $\Delta T_{\rm MI}$) while retaining a large TCR. For V_{1-x-y}Cr_xNb_yO₂ films, the conditions $x \gtrsim y$ and $x + y \ge 0.1$ are essential for obtaining large TCR values in excess of 10%/K and a near absence of thermal hysteresis ($\Delta T_{\rm MI} \le 0.6$ K), respectively. As seen in **Fig. 2(a)**, large TCR values of 16.7%/K with a $\Delta T_{\rm MI} \approx 0.9$ K or 13.6%/K with $\Delta T_{\rm MI} \approx 0.6$ K were attained with V_{0.90}Cr_{0.05}Nb_{0.05}O₂ (x = 0.05, y = 0.05) and V_{0.87}Cr_{0.08}Nb_{0.05}O₂ (x = 0.08, y = 0.05) films, respectively.

To further explore the optimal composition of the doped films, we examined the dependence of TCR and $\Delta T_{\rm MI}$ on x and y for $V_{1-x-y}Cr_xNb_yO_2$ films on Al₂O₃ substrates and we derived the diagram for the TCR and $\Delta T_{\rm MI}$ of the V_{1-x-y}Cr_xNb_yO₂ films shown in Fig. 3. As x and y increase, the TCR value decreases monotonically. Relatively large TCR values were obtained near the line x = y. Furthermore, the TCR contour lines/domains are asymmetric with respect to this line. This asymmetry indicates that a condition of $x \gtrsim y$ is suitable for obtaining a large TCR for $V_{1-x-y}Cr_xNb_yO_2$ films, as mentioned earlier. In contrast to the TCR, $\Delta T_{\rm MI}$ does not show a clear trend with x and y. However, the diagram confirms that a practical absence of thermal hysteresis can be obtained for co-doped $V_{1-x-y}Cr_xNb_yO_2$ films with x + $y \ge 0.1$. Therefore, because the total dopant content x + y should be as small as possible to obtain a large TCR, the optimal composition can be expected to be near the line x + y = 0.1 with the condition $x \ge y$, as shown by the solid circle in **Fig. 3**. In fact, among the films that showed practically no thermal hysteresis, the V_{0.90}Cr_{0.06}Nb_{0.04}O₂ film showed the best TCR of 16.2%/K.

Next, we will briefly discuss the effects of Cr and Nb co-doping on the MIT of VO₂. One of the important effects of Cr and Nb co-doping is that of charge compensation. Because Cr and Nb ions are trivalent and pentavalent, respectively, Cr and Nb co-doping of VO₂ has less overall effect on the change in the valence state of V4+ ions than does single-element doping. Therefore, any inhomogeneity of carrier concentration that results in a spatial variation in $T_{\rm MI}$ should be reduced in co-doped VO₂ films. As a result, broadening of the MIT is suppressed, leading to an improvement in the TCR of the co-doped films. However, because of the different ionic radii of V, Cr, and Nb ions, Cr and Nb co-doping still induces lattice deformations and defects in VO₂. We previously reported that Cr doping suppresses the lattice changes in VO₂ across the MIT that originate from a structural phase transition from a high-temperature tetragonal phase to a low-temperature monoclinic phase¹⁵⁾. The suppression of this lattice change in the doped films might be the cause of the decrease in the TCR and $\Delta T_{\rm MI}$. Because different doping elements induce different low-temperature monoclinic phases in $VO_2^{18,19,23)}$, the lattice change across the MIT in the co-doped films is expected to be more complicated than that in the single-element doped films. To gain a better understanding of the effects of co-doping on the TCR and $\Delta T_{\rm MI}$, detailed investigations of the structural properties of the co-doped VO₂ films are required, and will be a subject of a further study.

For uncooled bolometer applications, VO_2 films should be integrated onto Si platforms through a back-end-of-line (BEOL) process. We previously reported that TiO₂ buffer layers permit the fabrication

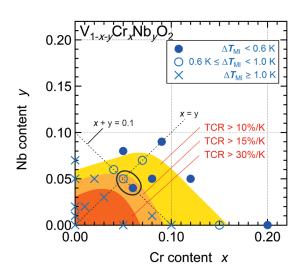


Fig. 3 TCR and ΔT_{MI} diagram for $V_{1-x-y}Cr_xNb_yO_2$ films as a function of the Cr and Nb contents. Values of ΔT_{MI} are divided into three categories: $\Delta T_{MI} \le 0.6$ K (filled circles), 0.6 K < $\Delta T_{MI} \le 1.0$ K (open circles), and $\Delta T_{MI} > 1.0$ K (crosses). The TCR values are classified into three regions: >10%/K, >15%/K, and >30%/K

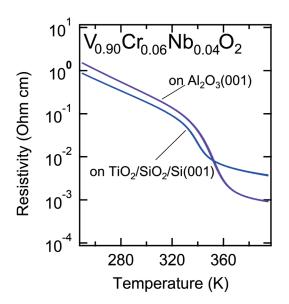


Fig. 4 Temperature dependence of the resistivity of $V_{0.90}Cr_{0.06}Nb_{0.04}O_2$ films on Al_2O_3 (0001) and TiO_2/ SiO_2/Si (100) substrates

of VO₂ films that show a sharp MIT on SiO₂/Si (100) substrates at process temperatures below 670 K, which is compatible with a BEOL process¹⁷⁾. By using the TiO₂-buffer technique, we deposited V₁₋ $_{x-y}Cr_xNb_yO_2$ films on SiO₂/Si (100) substrates to realize both large TCR values and an absence of thermal hysteresis. **Fig. 4** shows the ρ -T curves for the

 $V_{0.90}Cr_{0.06}Nb_{0.04}O_2$ films on Al_2O_3 and $TiO_2/SiO_2/Si$ substrates. As mentioned earlier, the film on the Al_2O_3 substrate showed practically no thermal hysteresis while retaining a large TCR of 16.2%/K. On the other hand, the film on the $TiO_2/SiO_2/Si$ substrate showed a reduced ρ change across the MIT but retained a large TCR of 11.9%/K. This result suggests that a combination of co-doping and the TiO_2 -buffer techniques provides an effective way of integrating a VO₂ film having large TCR values and a practical absence of thermal hysteresis on a Si platform.

4. SUMMARY

We have investigated the effects of co-doping of VO2 with Cr and Nb on the TCR and the thermal hysteresis of the MIT, and we have derived a TCR and $\Delta T_{\rm MI}$ diagram for V_{1-x-y}Cr_xNb_yO₂ films on Al₂O₃ substrates. The diagram showed that the doping conditions of $x \gtrsim y$ (i.e., a slightly Cr-rich condition) and $x + y \ge 0.1$ are suitable for simultaneously obtaining a large TCR and an absence of thermal hysteresis in the $V_{1-x-y}Cr_xNb_yO_2$ films. By employing Cr and Nb co-doping and the TiO₂-buffer technique, we succeeded in obtaining a large TCR value of 11.9%K with practically no thermal hysteresis in V_{0.90}Cr_{0.06}Nb_{0.04}O₂ films deposited on SiO₂/Si substrates at process temperatures below 670 K, which are compatible with a BEOL process. This combined technique might be applicable in the development of VO₂-based uncooled bolometers with a high sensitivity.

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著者



宮崎 憲一 みやざき けんいち

基礎研究2部 博士(工学) 半導体デバイスの研究開発に従事



鈴木 愛美 すずき めぐみ 基礎研究 2 部 半導体デバイスの研究開発に従事



酒井 賢一 さかい けんいち 基礎研究2部 半導体デバイスの研究開発に従事



法谷 圭介
しぶや けいすけ
(国研) 産業技術総合研究所
博士(科学)
酸化物エレクトロニクスの研究に従事



澤 彰仁 さわ あきひと (国研)産業技術総合研究所 博士(工学) 酸化物エレクトロニクスの研究に従事



藤田 淳一 ふじた じゅんいち 筑波大学数理物質系物理工学専攻教授,

応用理工学類学類長 博士(工学) グラフェンを利用したエレクトロニクスの 研究に従事